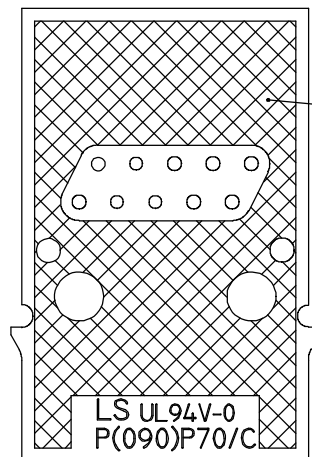
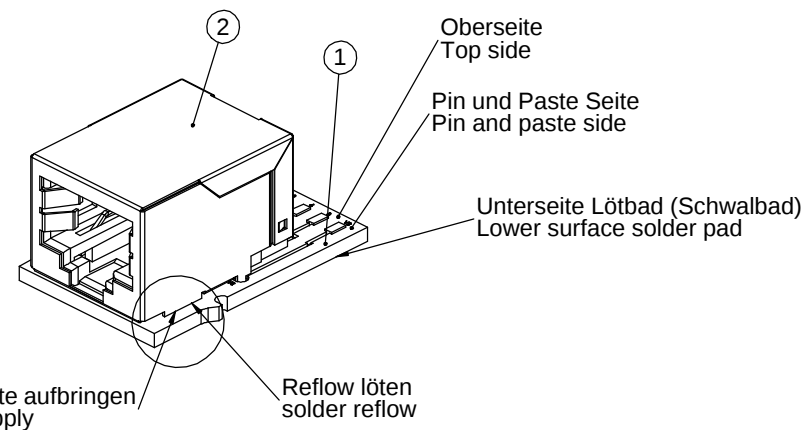


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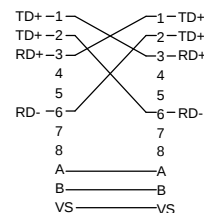


Unterseite Abschirmfläche
EMV (Kupferfläche + Lötstopplack) nach Absprache
Lower surface, shielding surface
EMV (copper surface + solder resist) as agreed



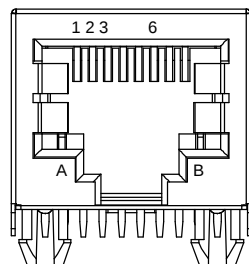
Note :

Standard Ethernet wiring



Die Kontaktverbindung ist nur schematisch zur Erklärung.
The contact connection is only for explanation
VS: Verbindung Schirm auf Lötbad
VS: Connection shielding on soldering pad

ITEM NO.	QUANTITY	DESCRIPTION	MATERIAL
1	1	P(090)P70 PCB	FR 4
2	1	Y-Con Jack 21	



UNLESS OTHERWISE SPECIFIED: DIMENSIONS ARE IN MILLIMETERS TOLERANCES: ± 0.2	REV.	REVISION DESCRIPTION	INITIALS	REV. DATE
	5			
	4			
	3			
	2			
NOTES: RJ45 Cat5	1			
	DO NOT SCALE DRAWING		CLASSIFICATION:	
	DESIGN	NAME	DATE	Customer-drawing
	DRAWN			TITLE: Y-Con Jack 23 PCB-Solder Pad
	CHECKED			DWG NO.: Customer-P(090)A70
ANGLE PROJECTION:	First	Q.A.		REV. ORIGIN C -
APPROVED				

